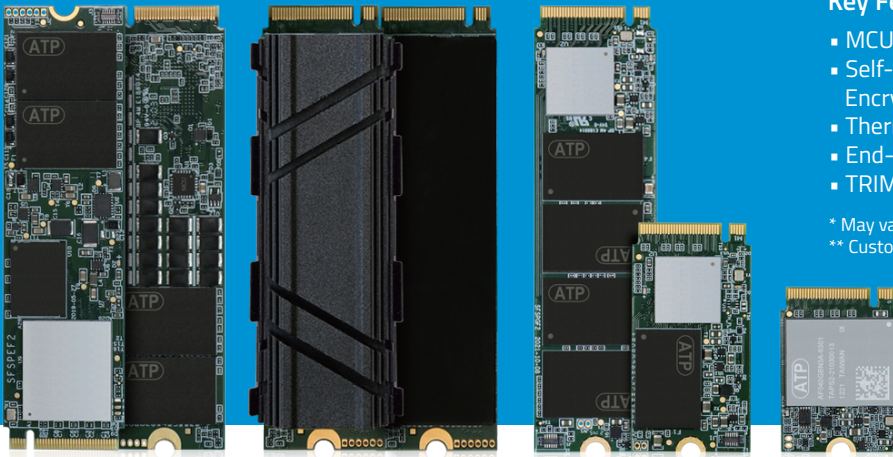




M.2 NVMe

Targeted Product Portfolio, Engineered Specifically for Your Mission Critical Applications



Key Features

- MCU-based Power Loss Protection Design *
- Self-Encrypting Drive (SED) with AES 256-bit Encryption, TCG OPAL 2.0*
- Thermal Management Solutions**
- End-to-End Data protection
- TRIM function support

* May vary by product and project support

** Customization available on a project basis.

M.2 solid state modules based on the NVMe™ protocol leverage the blazing-fast PCI Express® (PCIe®) interface to deliver dramatic improvements in speed and performance to fulfill the increasing demand for responsiveness in enterprise storage systems and to support the growing data-hungry needs of today's enterprise. Delivering 32 Gb/s bandwidth on a PCIe 3.1 x4 slot (8 Gb/s per lane), ATP NVMe SSDs outperform Serial ATA 6 Gb/s SSDs with 4-6X faster access, over 3X lower latency, and higher Input/Output per Second (IOPS). ATP NVMe SSDs with industrial operating temperature rating deliver stable performance even in extreme temperatures ranging from -40°C to 85°C, while Dynamic Thermal Throttling automatically adjusts the speed to maintain cooler operation under intense and heavy workloads.

Adopting NVMe 1.3 specifications and integrating 3D NAND TLC technology, ATP's M.2 2280 NVMe modules offer up to 1.92TB of storage capacity and deliver boosted performance with sequential read up to 3,420 MB/s, sequential write up to 3,050 MB/s, and random read/write IOPS up to 225,200/179,200.

Designed to move past the limitations of mechanical drives, NVMe was specifically built from the ground up for faster, more efficient access to storage devices with non-volatile memory such as current NAND flash solutions and future non-volatile memory technologies. These SSDs can deliver fast, reliable and durable performance for any demanding application.

Specifications

M.2 NVMe						
Product Line	Premium		Superior			
	N750Pi	N700Pi	N700Si	N700Sc	N650Si	N650Sc
Interface	PCIe G3 x4					
Flash Type	3D TLC (pSLC mode)		3D TLC (pSLC mode)		3D TLC	
Form Factor	M.2 2280-D2-M		M.2 2230-S4-M		M.2 2280-D2-M	
Operating Temperature (Tcase) ¹	-40°C to 85°C		-40°C to 85°C	0°C to 70°C	-40°C to 85°C	0°C to 70°C
Power Loss Protection Options	Hardware + Firmware Based		Firmware Based		Hardware + Firmware Based or Firmware Based	
Optional SED Features	AES 256-bit Encryption, TCG Opal 2.0					
Capacity	40 GB to 320 GB	40 GB to 640 GB	40 GB / 80 GB / 160 GB		120 GB to 960 GB	
Performance						
Sequential Read (MB/s) up to	3,150		2,000		3,420	
Sequential Write (MB/s) up to	2,670	2,820	1,600		3,050	
Random Reads IOPS up to	147,789 (4K, QD32)		135,600 (4K, QD32)		222,700 (4K, QD32)	
Random Writes IOPS up to	114,227 (4K, QD32)		112,000 (4K, QD32)		176,600 (4K, QD32)	
Endurance and Reliability						
Endurance (TBW) ² up to	16,000 TB	21,300 TB	4,280 TB		4,640 TB	
Reliability MTBF @ 25°C	>2,000,000 hours		>1,500,000 hours		>2,000,000 hours	
Others						
Dimensions: L x W x H (mm)	80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink)		30.0 x 22.0 x 2.5		80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink)	
Certifications	CE, FCC, BSMI, UKCA, RoHS, REACH					
Warranty	5 years		2 years			

M.2 NVMe						
Product Line	Superior		Value			
	N600Si	N600Sc	N600Vc	N600Vc	N600Vi	N600Vc
Interface	PCIe G3 x4					
Flash Type	3D TLC		3D TLC		3D TLC (TLC Mode)	
Form Factor	M.2 2280-D2-M		M.2 2280 S2-M	M.2 2242 D5-M	M.2 2230-S4-M	
Operating Temperature (Tcase) ¹	-40°C to 85°C	0°C to 70°C	0°C to 70°C		-40°C to 85°C	0°C to 70°C
Power Loss Protection Options	Hardware + Firmware Based or Firmware Based		Firmware Based			
Optional SED Features	AES 256-bit Encryption, TCG Opal 2.0		-			
Capacity	120 GB to 1,920 GB		120 GB to 960 GB		120GB / 240GB / 480GB	
Performance						
Sequential Read (MB/s) up to	3,420		2,600		2,000	
Sequential Write (MB/s) up to	3,050		1,870		1,570	
Random Reads IOPS up to	225,200 (4K, QD32)		184,300 (4K, QD32)		135,600 (4K, QD32)	
Random Writes IOPS up to	179,200 (4K, QD32)		145,900 (4K, QD32)		112,000 (4K, QD32)	
Endurance and Reliability						
Endurance (TBW) ² up to	5,585 TB		1,536 TB		768 TB	
Reliability MTBF @ 25°C	>2,000,000 hours		>2,000,000 hours		>1,500,000 hours	
Others						
Dimensions: L x W x H (mm)	80.0 x 22.0 x 3.5 (M.2 2280 Bare PCBA) 80.0 x 24.4 x 12.5 (M.2 2280 with 8 mm heatsink)		80.0 x 22.0 x 2.2	42.0 x 22.0 x 3.6	30.0 x 22.0 x 2.5	
Certifications	CE, FCC, BSMI, UKCA, RoHS, REACH					
Warranty	2 years					

¹ Case Temperature, the composite temperature as indicated by SMART temperature attributes.

² Under highest Sequential write value. May vary by density, configuration and applications.

Technologies & Add-On Services	S.M.A.R.T.	Hardware-based Power Loss Protection	AutoRefresh	Advanced Wear Leveling	Dynamic Data Refresh	End-to-End Data Protection	Secure Erase	TCG Opal 2.0	Industrial Temperature	Anti-Sulfur Resistors	Conformal Coating
Premium	○	○	○	○	○	○	▲	○	○	▲	▲
Superior	○	○	○	○	○	○	▲	○	▲	▲	▲
Value	○	○	○	○	○	○	-	-	-	▲	▲

▲: Customization option available on a project basis.